

**What is claimed is:**

1. (Currently Amended) ~~A process for producing a metal-ceramic substrate, in which at least one metal foil at a time is applied to a surface sides of a ceramic layer or a ceramic substrate using a high temperature bonding process and the metal foil is structured on at least one surface side for forming conductive tracks, contact surfaces, wherein after the high temperature bonding process at least one coating of a brazing resist is applied to the metal surface of the at least one metal foil or the at least one metal coating~~

A Process for producing a metal-ceramic substrate, the process comprising the following steps:

a) applying at least one metal foil to at least one surface side of a ceramic layer by high temperature bonding at a process temperature higher than 650°C for forming at least one metal coating on the ceramic layer,

b) structuring the metal coating on at least one surface side of the ceramic layer for forming a structured metal coating with conductive tracks and contact surfaces,

c) applying at least one coating of a brazing resist to the structured metal coating, and

d) removing some metal from the structured metal coating at least in surface areas bordering the brazing resist coating.

2. (Previously Presented) The process as claimed in claim 1, wherein high temperature bonding is carried out at a temperature greater than 650°C.

3. (Previously Presented) A process as claimed in claim 1, wherein high temperature bonding is a direct bonding process.

4. (Previously Presented) A process as claimed in claim 1, wherein high temperature bonding is an active brazing process.

5. (Previously Presented) A process as claimed in claim 1, wherein at least one coating of brazing resist is applied before structuring.

6. (Currently Amended) A process as claimed in claim 1, wherein at least one coating (~~5~~) of brazing resist is applied after structuring.

7. (Previously Presented) A process as claimed in claim 1, wherein the metal foils are copper foils and they are provided on the ceramic substrate by means of the DCB process or the active brazing process.

8. (Currently Amended) A process as claimed in claim 1, wherein structuring of the at least one metal foil takes place by means of masking-etching process and wherein the at least one coating (~~5~~) of brazing resist is applied immediately after this structuring.

9. (Currently Amended) A process as claimed in claim 1, wherein structuring of the at least one metal foil takes place by means of a masking-etching process using an etching resist and wherein the at least one coating (~~5~~) of brazing resist is applied immediately before application of the etching resist.

10. (Previously Presented) A process as claimed in claim 1, wherein after applying the brazing resist coating the metal of the metal coating is removed at least in the surface areas bordering this brazing resist coating.

11. (Previously Presented) A process as claimed in claim 10, wherein removal takes place by etching, using hydrogen peroxide, sodium persulfate, copper chloride or iron chloride.

12. (Previously presented) A process as claimed in claim 10, wherein removal takes place with a thickness from 0.1 to 20 microns.

13. (Previously Presented) A process as claimed in claim 1, wherein before the application of at least one brazing resist coating cleaning of the metal surfaces, by removing a surface area of the metal coatings, takes place.

14. (Currently Amended) A process as claimed in claim 13, wherein cleaning takes place by chemical removal ~~and/or~~ or by plasma etching ~~and/or~~ or by electrical etching ~~and/or~~ or galvanic removal ~~and/or~~ or by mechanical working, by brushing or grinding.

15. (Previously Presented) A process as claimed in claim 14, wherein chemical cleaning takes place using a hydrogen peroxide solution or a sodium persulfate solution.

16. (Previously Presented) A process as claimed claim 1, wherein a surface metal coating is applied to at least one surface area of the at least one metal coating, which area is produced by removal and adjoins at least one brazing resist coating.

17. (Previously Presented) A process as claimed in claim 16, wherein the surface metal coating is applied such that the surface which has been formed by this surface metal coating is level or roughly level with the surface of at least one brazing resist coating or level or roughly level with the untreated surface underneath at least one brazing resist coating.

18. (Previously Presented) A process as claimed in claim 16, wherein the surface metal coating is applied such that the surface which has been formed by this surface metal coating projects over the surface level of at least one brazing resist coating or over the surface level of the untreated surface underneath at least one brazing resist coating.

19. (Previously Presented) A process as claimed in claim 16, wherein the surface metal coating is applied such that the surface which has been formed by this surface metal coating is somewhat lower than the surface level of at least one brazing resist coating or of the untreated surface underneath at least one brazing resist coating.

20. (Currently Amended) A process as claimed in claim 1, wherein an epoxide-based resist coating is used for the brazing resist coating and wherein the brazing resist coating cures thermally.

21. (Previously Presented) A process as claimed in claim 1, wherein at least one brazing resist coating has a thickness of 0.5 to 100 microns.

22. (Previously Presented) A process as claimed in claim 1, wherein at least one brazing resist coating is structured in an area for forming an optically readable code.